



DT2042-01CSP

#### LOW CAPACITANCE UNIDIRECTIONAL TVS DIODE

## **Product Summary**

V <sub>BR</sub> Min	I <sub>PP</sub> Max	C <sub>IN</sub> Typ
6V	6.5A	0.8pF

### **Description**

This new generation TVS is designed to protect sensitive electronics from the damage due to ESD. The combination of small size and high ESD surge capability makes it ideal for use in portable applications such as cellular phones, digital cameras and MP3 players.

## **Applications**

- Cellular Handsets
- Portable Electronics
- · Computers and Peripheral

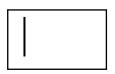
#### **Features**

- Provides ESD Protection per IEC 61000-4-2 Standard: Air ±20kV, Contact ±20kV
- Provides ESD Protection per IEC 61000-4-4 Standard: 40A (tp = 5/50ns)
- 1 Channel of ESD Protection
- Low Channel Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Mechanical Data**

- Case: X3-DSN1006-2 (Type B)
- Case Material: Chip Scale Package
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (Approximate)

X3-DSN1006-2 (Type B)







Top View

**Bottom View** 

**Device Schematic** 

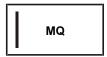
## Ordering Information (Note 4)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT2042-01CSP-7B	Standard	MQ	7	8	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



MQ = Product Type Marking Code Line Denotes Pin 1

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# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P <sub>PP</sub>	50	W	8/20µs (See Figure 1)
Peak Pulse Current	I <sub>PP</sub>	6.5	Α	8/20µs (See Figure 1)
ESD Protection – Air Discharge	V <sub>ESD_AIR</sub>	20	kV	IEC 61000-4-2 Standard
ESD Protection – Contact Discharge	V <sub>ESD_CONTACT</sub>	20	kV	IEC 61000-4-2 Standard

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	$P_{D}$	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Standoff Voltage	$V_{RWM}$		_	5	V	_
Channel Leakage Current (Note 6)	I <sub>RM</sub>	-	_	0.5	μA	V <sub>RWM</sub> = 5V
Breakdown Voltage	$V_{BR}$	6	_	10	V	I <sub>R</sub> = 10mA
Clamping Valtage Desitive Transients	VcL	-	7.0	7	V	$I_{PP} = 1A, t_P = 8/20 \mu s$
Clamping Voltage, Positive Transients		1	7.4	_	V	$I_{PP} = 2A, t_P = 8/20 \mu s$
Differential Resistance	R <sub>DYN</sub>	_	0.2	_	Ω	ITLP = 1A to 10A, t <sub>P</sub> = 100ns, I/O to GND
Channel Input Capacitance	CIN	_	0.8	_	pF	$V_R = 0V$ , $f = 1MHz$

Notes:

- 5. Device mounted on FR-4 PCB pad Jayout (2oz copper) per Diodes Incorporated's recommended pad Jayout, refer to http://www.diodes.com/package-outlines.html.

  6. Short duration pulse test used to minimize self-heating effect.





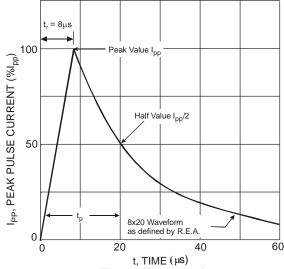
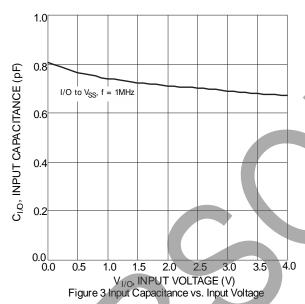
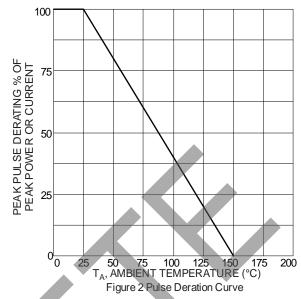
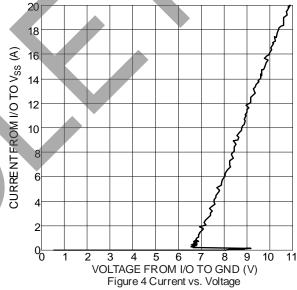


Figure 1 Pulse Waveform





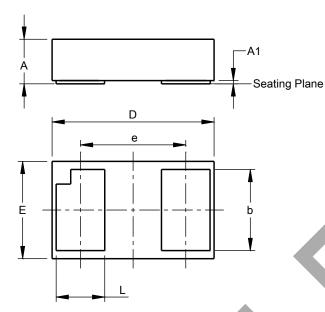




# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X3-DSN1006-2 (Type B)

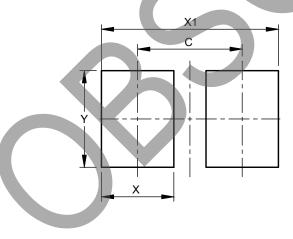


X3-DSN1006-2 (Type B)					
Dim	Min	Max	Тур		
Α	0.250	0.300	0.275		
A1	0.00	0.02	0.01		
b	0.490	0.510	0.500		
D	0.975	1.025	1.00		
E	0.575	0.625	0.600		
е			0.650		
L	0.290	0.310	0.300		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X3-DSN1006-2 (Type B)



Dimensions	Value (in mm)		
C	0.65		
Х	0.45		
X1	1.10		
Y	0.60		

Note 7: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.



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